REMARKS

Original claims 1-56 have been canceled, and new claims 57-82 have been added. A reading of the new claims on the drawings and specification is as follows.

57. A semiconductor package **(16-Figure 2E or 16A-Figure 5)** comprising:

a leadframe **(28-Figure 2E)**;

a die **(32-Figure 2E)** on the leadframe; and

a plastic body **(18-Figure 2E)** comprising a first polymer member **(inner member 42-Figure 2E)** on the die or the leadframe, and a second polymer member **(outer member 44-Figure 2E)** encapsulating the first polymer member **(page 6, lines 31-33)**, the first polymer member and the second polymer member configured to adjust a selected characteristic of the package **(page 6, lines 8-9; page 6, lines 15-18; page 13, lines 15-20)**.

58. The semiconductor package of claim 57 wherein the selected characteristic comprises a package bow **(page 6, line 19)**.

60. The semiconductor package of claim 57 wherein the selected characteristic comprises a package warpage **(page 4, line 10)**.

61. The semiconductor package of claim 57 wherein the first polymer member comprises a molded material **(page 6, line 3)**.

62. The semiconductor package of claim 57 wherein the first polymer member comprises a tape material **(page 15, lines 30-33)**.

63. The semiconductor package of claim 57 wherein the first polymer member encapsulates the die **(page 6, lines 4-5)**.

64. The semiconductor package of claim 57 wherein the first polymer member and the second polymer member are selected to provide a substantially equal volume of a molding compound on either side of the leadframe **(page 6, lines 12-14)**.

65. A semiconductor package **(16-Figure 2E or 16A-Figure 5)** comprising:

a leadframe **(28-Figure 2E)**;

a die **(32-Figure 2E)** on the leadframe;

a first polymer member **(inner member 42-Figure 2E)** on the die or the leadframe; and

a second polymer member **(outer member 44-Figure 2E)** encapsulating the first polymer member;

the first polymer member and the second polymer member having selected geometries **(page 11, lines 2-6)** configured to provide a selected characteristic for the package **(page 6, lines 8-9; page 6, lines 15-18; page 13, lines 15-20)**.

66. The semiconductor package of claim 65 wherein the selected geometries comprise volumes of a molding compound **(page 6, lines 12-14)**.

67. The semiconductor package of claim 65 wherein the selected geometries are configured to reduce a package bow **(page 6, line 19)**.

68. The semiconductor package of claim 65 wherein the selected geometries are configured to reduce a package warpage **(page 4, line 10)**.

69. The semiconductor package of claim 65 wherein the first polymer member comprises a molding compound substantially encapsulating the die **(page 6, lines 4-5)**.

70. The semiconductor package of claim 65 wherein the first polymer member and the second polymer member comprise a molded plastic **(page 13, lines 31-33)**.

71. A semiconductor package **(16-Figure 2E or 16A-Figure 5)** having a parting line **(40-Figure 2E)** comprising:

a leadframe **(28-Figure 2E)**;

a die **(32-Figure 2E)** on the leadframe;

a polymer member **(inner member 42-Figure 2E)** on the die or the leadframe; and

a plastic body **(18-Figure 2E)** comprising a molding compound encapsulating the polymer member and at least a portion of the leadframe **(page 6, lines 31-33)**;

the polymer member configured to provide a substantially equal volume of the molding compound on either side of the parting line **(page 6, lines 12-14)**.

72. The semiconductor package of claim 71 wherein the polymer member comprises a material selected from the group consisting of epoxy, silicone, room temperature vulcanizing (RTV) and polyimide **(page 15, lines 24-25)**.

73. The semiconductor package of claim 71 wherein the polymer member comprises a tape material **(page 15, lines 30-33)**.

74. The semiconductor package of claim 71 wherein the polymer member encapsulates the die **(page 6, lines 29-31)**.

75. The semiconductor package of claim 71 wherein the leadframe has a lead-on-chip configuration **(page 9, line 30)**.

76. The semiconductor package of claim 71 wherein the die is attached **(page 12, line 10)** and wire bonded **(page 12, lines 13-15)** to the leadframe.

77. The semiconductor package of claim 71 wherein the polymer member comprises the molding compound **(page 13, lines 31-33)**.

78. A semiconductor package **(16-Figure 2E or 16A-Figure 5)** comprising:

a leadframe **(28-Figure 2E)**;

a die **(32-Figure 2E)** on the leadframe; and

a first polymer member **(inner member 42-Figure 2E)** on the die or the leadframe; and

a second polymer member **(outer member 44-Figure 2E)** on the first polymer member and the leadframe;

the first polymer member configured to provide a selected characteristic in the second polymer member **(page 13, lines 15-20)**.

79. The semiconductor package of claim 78 wherein the selected characteristic comprises increased rigidity **(page 6, lines 8-9)**.

80. The semiconductor package of claim 78 wherein the second polymer member comprises substantially equal volumes of a molding compound on either side of the leadframe **(page 6, lines 12-14)**.

81. The semiconductor package of claim 78 wherein the first polymer member substantially encapsulates the die **(page 6, lines 4-5)**.

82. The semiconductor package of claim 78 wherein the second polymer member substantially encapsulates the first polymer member **(page 6, lines 31-33)**.

Conclusion

Favorable consideration and allowance of claims 57-82 is respectfully requested. An Information Disclosure Statement is being filed concurrently with this Preliminary Amendment. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

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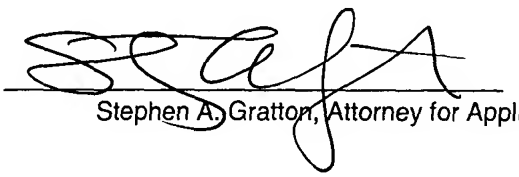

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